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AMMENDMENTS TO THE CLAIMS

What is claimed is:

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1. (currently amended) A mold or former for producing a natural or synthetic rubber article having on its surface a release composition comprising:
- a) ~~a water-borne high-Tg~~ an emulsion polymer formed from:
- (1) at least one hydrophobic monomer; and
- (2) at least one hydrophilic monomer,
- wherein said ~~water-borne~~ emulsion polymer has a Tg of at least -10°C, and
- b) a rheology modifier.
2. (currently amended) The mold or former of claim 1 wherein said ~~water-borne~~ emulsion polymer comprises an emulsion polymer.
3. (currently amended) The mold or former of claim 2 wherein said ~~water-borne~~ emulsion polymer has a particle size of from 0.05 to 1.5 microns.
4. (currently amended) The mold or former of claim 3 wherein said ~~water-borne~~ emulsion polymer has a particle size of from 0.15 to 0.9 microns
5. (original) The mold or former of claim 1 wherein said hydrophobic monomer comprises styrene.
6. (original) The mold or former of claim 1 wherein said hydrophilic monomer is an acid monomer.
7. (original) The mold or former of claim 1 wherein said mold release composition further comprises a surfactant.
8. (original) The mold or former of claim 1 wherein said release composition further comprises microspheres.
9. (original) The mold or former of claim 1 wherein said release composition further comprises a dispersant.
10. (currently amended) The mold or former of claim 1 wherein said ~~water-borne~~ emulsion polymer further comprises a cross-linker.
11. (currently cancelled)
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12. (original) The mold or former of claim 1 wherein said release composition further comprising a coagulant.

13. (currently amended) The mold or former of claim 1 wherein said ~~high-Tg~~ emulsion polymer comprises:

- a) from 20 to 35 percent by weight of methacrylic acid;
- b) from 65 to 80 percent by weight of styrene; and
- c) from 0.5 to 1.5 percent by weight of a crosslinker.

14. (original) The mold or former of claim 1 wherein said release composition is free of silicon compounds.

Claims 15 to 24 (Previously Withdrawn)